



## Product Change Notification / JAON-17DZYV010

---

**Date:**

01-Oct-2021

**Product Category:**

Memory

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4560 Final Notice: Qualification of SIGN as a new assembly site for selected SST39LF80xx, SST39VF160xx and SST39VF80xx device families available in 48L TSOP (12x20mm) package.

**Affected CPNs:**

[JAON-17DZYV010\\_Affected\\_CPN\\_10012021.pdf](#)

[JAON-17DZYV010\\_Affected\\_CPN\\_10012021.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of SIGN as a new assembly site for selected SST39LF80xx, SST39VF160xx and SST39VF80xx device families available in 48L TSOP (12x20mm) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change

Assembly Site	Lingsen Precision Industries, LTD. (LPI)		Signetics Corporation (SIGN)	
Bond Wire material	Au		Au	
Die Attach material	8340		AP-4300	
Mold compound material	G700		G700	
Lead frame material	C7025		C7025	
DAP Surface plating	Ring /Selective Plating		Ring /Selective Plating	
Lead frame paddle size	207x142mils Note 1	160x130mils Note 2	209x165mils Note 1	159x165mils Note 2
	See attached pre and post change comparison.			

Note 1: Applicable for SST39VF160xx device family.

Note 2: Applicable for SST39LF80xx and SST39VF80xx device families

**Impacts to Data Sheet:**None

**Change Impact**None

**Reason for Change:**To improve on-time delivery performance by qualifying SIGN as a new assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**October 31, 2021 (date code: 2145)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	February 2021					>	October 2021					
Workweek	0	0	0	0	1		4	4	4	4	4	4
	6	7	8	9	0		0	1	2	3	4	5
Initial PCN Issue Date				x								

Qual Report Availability								X				
Final PCN Issue Date								X				
Estimated Implementation Date												X

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**February 19, 2021: Issued initial notification.

April 08, 2021: Re-issued initial notification to update the pre and post comparison table to modify SIGN die attach material from 8340 to AP-4300. Updated LPI DAP surface plating from Ring plating to Ring /Selective plating and updated SIGN DAP surface plating from Double ring plating to Ring /Selective plating. Updated the Qual plan summary to modify SIGN die attach material from 8340 to AP-4300 and to modify SIGN DAP surface plating from Double ring plating to Ring /Selective plating.

October 1, 2021: Issued final notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

- [PCN\\_JAON-17DZYV010\\_Qual Report.pdf](#)
- [PCN\\_JAON-17DZYV010\\_Pre and Post Change\\_Summary.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.